



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR POWERPAK® MLP55					
STRESS	SAMPLE SIZE	DEVICE HRS./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
Bond Integrity	82	41 000	200 °C + N2	0	0.00
HAST	246	24 600	130 °C, 85 % RH	0	0.00
Pressure Pot	246	23 616	121 °C, 15 PSIG	0	0.00
Solder Dunk	164	492	260 °C, 10 s	0	0.00
Temp. Cycle	246	246 000	-65 °C to +150 °C	0	0.00